

| FORM PTO-1449 (Rev. 7-80) | | U.S. Department of Commerce Patent and Trademark Office | | Atty. Docket No. TESSERA 3.0-109 CIP DIV | | Application No. | |
|---|----|--|---------|---|-------|-----------------|----------------------------|
| LIST OF PRIOR ART CITED BY APPLICANT <i>(Use several sheets if necessary)</i> | | | | Applicant <i>Kim, et al.</i> | | | |
| | | | | Filing Date: February 2, 2001 | | Group | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| *EXAMINER INITIALS | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
| <i>G</i> | AA | 4,941,033 | 7/10/90 | Kishida | 357 | 75 | |
| | AB | 5,148,265 | 9/15/92 | <i>Khandros et al.</i> | 357 | 80 | |
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| | AD | 5,347,159 | 9/13/94 | <i>Khandros et al.</i> | 257 | 692 | |
| | AE | 5,390,844 | 2/21/95 | <i>DiStefano et al.</i> | 228 | 180.21 | |
| | AF | 5,398,863 | 3/21/95 | <i>Grube et al.</i> | 228 | 106 | |
| | AG | 5,491,302 | 2/13/96 | <i>DiStefano et al.</i> | 114 | 260 | |
| | AH | 5,536,909 | 7/16/96 | <i>DiStefano et al.</i> | 174 | 261 | |
| | AI | 5,646,446 | 7/8/97 | <i>Nicewarner, Jr. et al.</i> | 257 | 723 | |
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| <i>G</i> | AK | 5,861,666 | 1/19/99 | Bellaar | 257 | 686 | |
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| <i>G</i> | AL | 2 312 172 | | France | | | |
| <i>G</i> | AM | 0 080 041 A2 | 06/83 | Europe | | | |
| <i>G</i> | AN | WO 94/03036 | 02/94 | WIPO | | | |
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| <i>G</i> | AR | Bill Chou et al., "Ultra-High-Density Interconnect Flex Substrates", High Density Interconnects, 12/1998, pp. 14-21 | | | | | |
| <i>G</i> | AS | Rudolf Leutenbauer et al., "Development of a Top-Bottom BGA", High Density Interconnects, 12/1998, pp. 28-32 | | | | | |
| <i>G</i> | AT | Daryl Ann Doane and Paul D. Franzon, "Packaging Performance Factors," Multichip Module Technologies and Alternatives: The basics, pp. 109-112, ©1993 by Van Nostrand Reinhold. | | | | | |
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| *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | |
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(Rev. 7-80)U.S. Department of Commerce
Patent and Trademark OfficeAtty. Docket No.
TESSERA 3.0-109 CIP DIV

Application No.

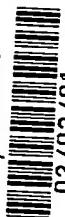
LIST OF PRIOR ART CITED BY APPLICANT

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Kim, et al.

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| | AB | 3,214,827 | 11/65 | Phohofsky | 29 | 155.5 | |
| | AC | 3,775,844 | 12/73 | Parks | 29 | 626 | |
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| | AI | 5,198,888 | 03/93 | Sugano et al. | 257 | 686 | |
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| *EXAMINER INITIALS | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
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| <i>Ch</i> | AA | 5,281,852 | 01/94 | Normington | 257 | 685 | |
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| | AI | 5,479,318 | 12/95 | Burns | 361 | 735 | |
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| <i>G</i> | AK | 5,659,952 | 08/97 | Kovac et al. | 29 | 840 | |

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